

Specifications

1.0 Features

- 640 x 512 Pixels
- Snapshot Mode
- Integrate-Then-Read
- P on N Input Polarity
- > 7 Million Electron Well Capacity (3 Million ISC9901-2 Option)
- Selectable, 1 to 4 Outputs
- Dynamic Image Transposition

Image Invert [top-to-bottom]

Image Revert [left-to-right]

- Dynamic Windowing Readout
- Interlaced/non-interlaced readout
- Selectable Differential Output Mode
- On-Chip DACs control

Power Adjust

- Variable Gain
- Signal ‘Skimming’
- Buffered Temperature Sensor Output
- Adjustable Power
 - Low Power Operation
 - High Speed Operation
- Two Operational Modes
 - Simple ‘hands-off’ Default Mode
 - User Configurable Command Mode
- Tested Wafer w/ Wafer Map and Die Data.
- Detector Applications
 - InSb, InGaAs, MCT, or QWIP

2.0 Product Description

The ISC9901 is a high performance, 640 x 512 pixel, readout integrated circuit (ROIC) with snapshot mode integration. This state-of-the-art ROIC is suitable for use with p on n detector materials such as indium antimonide (InSb), mercury cadmium telluride (MCT), quantum well infrared photo diodes (QWIPs) and indium gallium arsenide (InGaAs). A simplified ‘hands-off’ Default Mode directly supports single output NTSC or PAL operation. Using the Command Mode, the ISC9901 supports advanced features including; dynamic image transposition, dynamic windowing, interlaced/non-interlaced readout, multiple output configurations, power adjustment, and signal ‘skimming’. The device also supports variable gain and biasing for high reverse bias detectors.

Using four 10MHz outputs, frame rates up to 97 frames per second can be achieved for a 640 x 480 pixel frame (Tint=1ms). Using the dynamic windowing mode, small windows can be read out at > 930 frames per second. A convenient buffered temperature sensor output is

available for monitoring of the ROIC substrate temperature.

The ISC9901 is fabricated using an advanced 0.6 micron double poly, triple metal process which utilizes high speed CMOS transistors. High speed, precision analog circuits are combined with high density digital logic circuits. The ISC9901 is delivered in wafer form and is specified for operation from 80 K to 300 K.

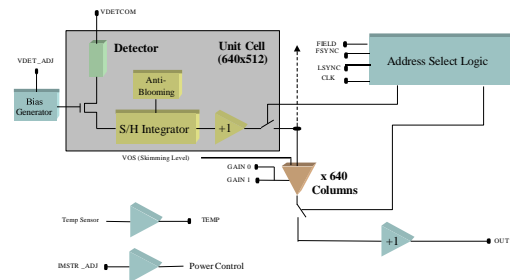


Figure 1. ISC9901 Block Diagram

Figure 1 shows the block diagram for the Default Mode

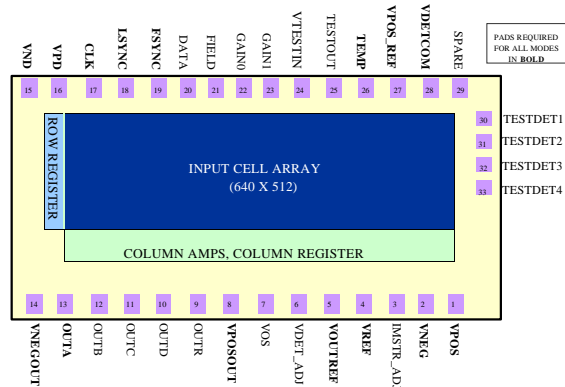


Figure 2. ISC9901 Pinout

operation. The detector bias generator is adjustable using the VDET_ADJ pad. The unit cell uses a direct injection topology with an anti-blooming transistor. The output from each unit cell is then addressed to a column bus and sampled onto a variable gain column amplifier. The column amplifier is multiplexed to a single output. A skimming function is also provided to globally offset the output signal for high leakage current detectors such as QWIPs. An on-chip temperature sensor is available through the TEMP pad. Power control is accomplished by applying a voltage to the IMSTR_ADJ pad. The ISC9901 pad definition is shown in Figure 2. The pads required for both operation modes appear in bold type.

3.0 Specifications

Maximum Ratings				
Parameter	With Respect To	Min.	Max.	Units
VPOS, VPD, VPOSOUT	VNEG, VND, VNEGOUT, Vsub	-0.5 ²	5.7 ¹	Volts
Vref	VNEG, VND, VNEGOUT, Vsub	-0.5 ²	VPOS ¹	Volts
Clock Inputs	VNEG, VND, VNEGOUT, Vsub	-0.5 ²	VPD + 0.2 ¹	Volts
Outputs	VNEG, VND, VNEGOUT, Vsub	0.0 ²		Volts
Operating Temperature		50 ²	310 ²	K
Storage Temperature		49 ²	420 ²	K

NOTES:

1. Stresses above the value listed may cause permanent damage to the device.
2. Stresses beyond the listed range may cause permanent damage to the device. This is a stress rating *only*. Functional operation of the device at these or other conditions above those indicated in the operational sections of this specification are not implied. Exposure to maximum ratings for extended periods of time may affect device reliability.

Mechanical Specifications					
Parameter	Test Level	Min.	Typ.	Max.	Units
Wafer Size	V		5		Inch
Total Die per Wafer ¹	V		37		Die/wafer
Detector Columns	IV		640		Active unit cells
Detector Rows	IV		512		Active unit cells
Detector Row and Column Pitch	IV		20		µm
Die Size ²	IV		14.65 x 14.71		mm
Scribe Lanes in X and Y	IV		200		µm

NOTES:

1. Including all die grades
2. As measured to edge of scribe lane

EXPLANATION OF TEST LEVELS

Test Level

- I – 100% production tested.
- II – 100% production tested at room temperature.
- III – Sample tested only.
- IV – Parameter is guaranteed by design and/or characterization testing.
- V – Parameter is a typical value only.
- VI – All devices are 100% production tested at room temperature.

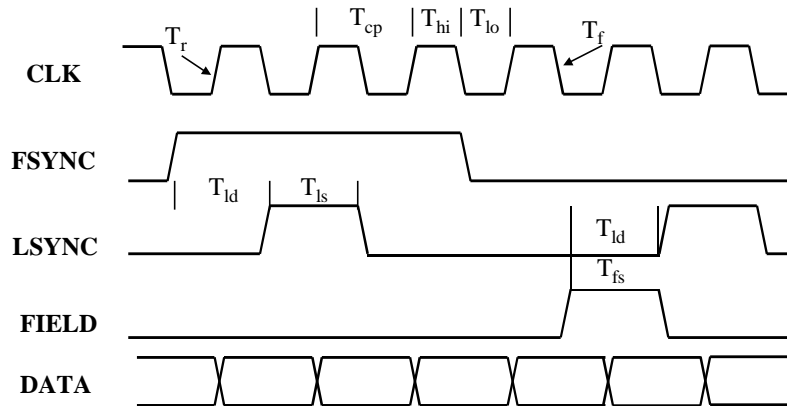
DC Specifications (50-300K operation unless noted)					
Parameter	Test Level	Min.	Typ.	Max.	Units
Output Rate, Single output mode (80 or 300K) ⁶	II			12.3	Mpixels
Output Rate, 2 or 4 output mode (80 or 300K) ⁶	IV			10	MPixels
Max 640 x 480 Window Frame Rate @80K					
4 Output Mode (Tint=1ms, max power)	Note 13			95	Frames/sec
2 Output Mode (Tint=1ms, max power)	Note 13			55	Frames/sec
1 Output Mode (Tint=1ms, max power)	Note 13			30	Frames/sec
Max Frame Rate @ 80K, min. window size					
4 Output Mode, max power 128 x 8	IV			930	Frames/sec
2 Output Mode, max power 64 x 8	IV			930	Frames/sec
1 Output Mode, max power 32 x 8	IV			930	Frames/sec
Output Voltage Swing ⁹	VI	2.1	2.6	2.9	Volts
Output Voltage Low ⁶	V	1.4	1.6	1.8	Volts
Output Voltage High ⁶	V	3.9	4.1	4.3	Volts
Input Clock Rate	IV	DC	3	6.15 ¹⁵	MHz
Output Noise⁸					
Gain 00	IV		123		µV
Gain 01	IV		145		µV
Gain 10	IV		182		µV
Gain 11	IV		302		µV
Equiv. Integration Capacitor Input Noise⁸					
Gain 00	IV		321		e ⁻
Gain 01	IV		284		e ⁻
Gain 10	IV		238		e ⁻
Gain 11	IV		197		e ⁻
Gain					
Gain 00 (Relative Gain 1.0)	IV		0.46		µV/e ⁻
Gain 01 (Relative Gain 1.33)	IV		0.61		µV/e ⁻
Gain 10 (Relative Gain 2.0)	IV		0.91		µV/e ⁻
Gain 11 (Relative Gain 4.0)	IV		1.83		µV/e ⁻
Transimpedance Non-Linearity ¹⁰	IV		±0.1%	<0.5%	
Unit Cell Input					
Detector Capacitance ⁷	IV			≤ 0.5	pf
Detector Impedance ⁷	IV	> 1e+03			Ohms*cm ²
Full Well Capacity 350fF Cint (150fF) ¹¹ , @3.2V	IV	6.3e ⁶ (2.7e ⁶)	7e ⁶ (3e ⁶)	7.7e ⁶ (3.3e ⁶)	e ⁻
Input Current ⁷	IV	.001	1.0	10	nA

NOTES:

1. Category IV for specified min., category VI for specified max.
2. Category IV for specified min. and max., category VI for specified typ.
3. Voltages below V_{nd} may cause excess power dissipation.
4. Voltages above V_{pd} may cause excess power dissipation.
5. Typical value tested
6. ≤0.25pf max., >100K ohms min.
7. Simulation range.
8. Zero detector current.
9. Imstr_adj set for 100 uA
10. As measured by output voltage vs Tint; Max deviation from a least squares fit over 10% to 80% full well.
11. ISC9901-2 Version
12. Relative gain measured.
13. Category IV for 80K, category VI 300K.
14. For high reverse bias configurations (e.g. QWIP)
15. Output pixel rate is twice the input clock rate

DC Specifications (cont)	Test Level	Min.	Typical	Max.	Units
Operability					
Percentage		99.998			%
Bad Pixel Cluster Size				50	pixels
On Chip Detector Bias DAC Input					
Voltage Range (forward to reverse bias)	VI	-195 to 425 (300K)	-120 to 520 (80K)		mV
DAC Bits	V		7		
Voltage Resolution	VI		5		mV/count
Temperature Sensor Output @ 300K	V	0.65	0.70	0.75	Volts
Temperature Sensor Output @ 78K	IV	1.02	1.070	1.12	Volts
Power Supply Voltages (wrt VNEG,VND,VNEGOUT,Vsub)					
VDETCOM	Note 1	0	5.5	6.0 ¹⁴	Volts
VPOS	Note 1	5.3	5.5	5.7	Volts
VPOSOUT	Note 1	5.3	5.5	5.7	Volts
VPD	Note 1	5.3	5.5	5.7	Volts
Reference and Control Voltage Inputs					
VREF	Note 2	1.5	1.6	1.7	Volts
VOUTREF	Note 2	1.5	1.6	1.7	Volts
VDET_ADJ		0		5.5	Volts
IMSTR_ADJ	IV	0	3	5.5	Volts
VOS	IV	VREF		VPOS	Volts
Power Supply Currents					
VDETCOM	V		<1	<10 (peak)	mA
VPOS	V		<17	<60 (peak)	mA
VPOSOUT	V		<25	<80 (peak)	mA
VPD	V		<4	<60 (peak)	mA
Logic Inputs					
Input Low Voltage	II	VND - 0.2 ³	VND	VND + 0.2	Volts
Input High Voltage	II	VPD - 0.2	VPD	VPD + 0.2 ⁴	Volts
Power Consumption⁹					
Single Output NTSC/PAL	IV		90		mW
Four Output Max Frame Rate	IV		180		mW
Integration Time 640 x 480	IV	0.1	User adjustable		msec
1 Output @ 12.3MHz, Interlaced				≥ 6.5 msec @ 30Hz Frame Rate	
4 Outputs @ 10MHz, Non-Interlaced				≥ 7.35 msec @ 60Hz Frame Rate	

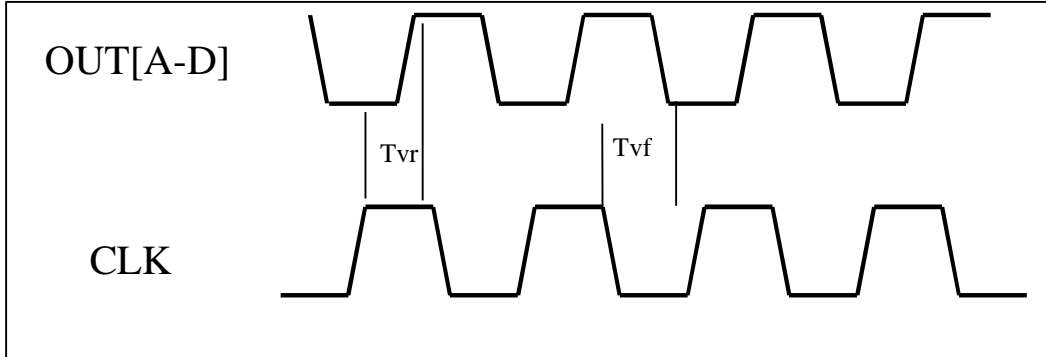
Switching Specifications					
Full Temperature Range					
Parameter	Name	Min.	Typ.	Max.	Units
Trise	Tr			10	ns
Tfall	Tf			10	ns
Tsetup/ hold:all signals to CLK edge	Tsh	5			ns
Clock Duty Cycle (6.15MHz clk rate)	Tcp	162.6			ns
Clock High, 50% duty cycle	Thi		Tcp * 0.5		ns
Clock Low, 50% duty cycle	Tlo		Tcp * 0.5		ns
FSYNC to LSYNC delay and FIELD to LSYNC delay	Tld	≥1*Tcp			clocks
LSYNC width	Tls	1*Tcp			clocks
FIELD width	Tfs	≥1*Tcp			ns
DATA valid settling time			≤55 to 0.1% (80K) to 0.39% (300K)	≤65 to 0.1% (80K) to 0.39% (300K)	ns



AC Specifications					
Full Temperature Range					
Parameter	Name	Min.	Typ.	Max.	Units
Clock rise to video output settled delay ¹	Tvr		75	95	ns
Clock fall to video output settled delay ¹	Tvf		75	95	ns
Crosstalk(non-adjacent pixels)	Xt		<.05%(80K)	<0.2% (300K)	
Crosstalk (adjacent pixel)	Xta		<0.1%(80K)	<0.39% (300K)	

Notes:

1. Video data appears on both the rising and falling edges of the clock, data settling to 0.1% at 80K



4.0 Pinout Descriptions

DIGITAL PINS			
Chip Pin	Signal Name	Description	I/O type
23 22	GAIN1 GAIN 0	External Gain: These pins are used to control the gain of the chip when operating in Default Mode, they are not used in Command Mode. There are internal pull down resistors on each pin. See the DC Specification for the relative gain settings.	DI
21	FIELD	Interlace/Non-Interlace Controls reading out the even field when the device is set to Interlace readout mode by setting the Serial Control Register bit RO0 high	
20	DATA	Serial Control Register Data: This digital input is used to program the Serial Control Register when operating the chip in Command Mode. This input is not connected in Default Mode and is internally pulled down.	CI
19	FSYNC	Frame Sync: This signal is used to sync the start of a frame, invoke new commands loaded in the Serial Control Register and control the integration time. Frames are synced and Serial Control Register words are loaded on the rising edge of FSYNC. Integration time is started on the falling edge of FSYNC.	CI
18	LSYNC	Line Sync: This signal controls the readout synchronization of each individual row on the array. A sequence of LSYNC pulses produces a readout sequence. The rising edge of LSYNC is synchronous with the falling edge of CLK.	CI
17	CLK	Data Output and Command Data Stream Clock: This signal is used to load commands on the DATA input pin into the Serial Control Register and to read out pixel data on OUTA-D. Pixel data is clocked on both the rising and falling edge of CLK. Data is loaded into the Serial Control Register only on the falling edge of CLK.	CI

Explanation of I/O Type Symbols:
 AO - Analog Output: Low bandwidth analog output.
 DI - Digital Input: Low speed digital signal.
 CI - Clock Input: High speed digital signal.
 CO - Clock Output: High speed digital output.
 P - Power Supply: Power supply or power supply return [ground].
 R - Reference Voltage: DC voltage reference
 TA - Test Analog Input: DC test voltage
 TD - Test Detector I/O: Test detector access [used to test detectors after hybridization]
 VO - Video Output: High speed video output pin.

Analog Pins			
Chip Pin	Signal Name	Description	I/O Type
13	OUTA	Video Output A: Chip output pin, used for both Default and Command Mode operation in 1, 2, and 4 output modes.	VO
12	OUTB	Video Output B: Chip output pin for the for Command Mode operation in 2 and 4 output modes.	VO
11	OUTC	Video Output C: Chip output pin for the for Command Mode operation in 4 output.	VO
10	OUTD	Video Output D: Chip output pin for the for Command Mode operation in 4 output mode.	VO
9	OUTREF	Common Mode Reference Output: This pin provides a buffered version of Voutref for systems which use common mode noise reduction techniques. This output is the Voutref signal routed through a buffer amplifier identical to those used for the video output signals, used in Command Mode only	VO
26	TEMP	Buffered Temperature Diode: This pin may be used to read the temperature of the chip.	AO
5	VOUTREF	Analog Output Reference Voltage: 1.6 volts, care should be taken to prevent Voutref and Vref from AC coupling.	R
7	VOS	Skimming Voltage: Provides a means of subtracting a constant voltage from the detector signals prior to the column amplifier stage. In Command Mode it is enabled/disabled through the Serial Control Register.	R
4	VREF	Analog Reference Voltage: 1.6 volts, care should be taken to prevent Voutref and Vref from AC coupling.	R
6	VDET_ADJ	Detector Bias Adjustment: This pin provides a means to set the detector bias voltage in Default Mode. The voltage set at this pin depends on the type of detectors, detector processing and operating temperature. In Command Mode, the Serial Control Register is used to adjust detector bias and this pad can be used to monitor the setting.	R
3	IMSTR_ADJ	Master Current Adjustment: This pin provides a means to adjust the master current source level in Default Mode. In Command Mode the master current is adjusted through the Serial Control Register and this pad is not connected. For Default Mode 300K operation this pad must be tied to GND.	R

Power Supply and Ground Pins			
Chip Pin	Signal Name	Description	I/O Type
28	VDETCOM	Detector Common: Detector Positive Supply, connected to the “detector common hybridization ring. This is a ring of 6 connection points that surround the active detector area. Note: Must be connected and biased for correct operation.	P
27	VPOS_REF	Low Voltage Detector VDETCOM Supply: This pin is used to power VDETCOM for low reverse bias detectors. It must be tied to the VDETCOM pad, by the user.	P
1	VPOS	Analog Supply: This is the positive supply for all analog circuits on the chip except the output multiplexer and buffer circuits.	P
16	VPD	Digital Supply: This is the positive supply for all the digital circuits.	P
8	VPOSOUT	Output Supply: This is the positive supply for the output multiplexer and buffer circuits that drive OUTA-D and OUTR. This supply is the largest AC current carrying node on the chip. Care should be taken to provide a low ESR capacitor path for this node, bypassed to VNEGOUT. Other positive supplies should be isolated from the relatively large AC currents carried by this pad.	P
15	VND	Digital Return: Ground node for all the digital circuits on the chip.	P
14	VNEGOUT	Output Ground: This ground node sinks the output amplifiers that drive the output multiplexer, OUTA-D and OUTR. This is the largest current carrying ground node on the chip and care should be taken to provide a low ESR capacitor path for this node.	P
2	VNEG	Analog Ground: Ground for all the analog circuits except the output multiplexer and buffers. This node is connected to the substrate (Vsub). Care should be taken to minimize inductance to this pad.	P

Special Use Pins			
Chip Pin	Signal Name	Description	I/O Type
24	VTESTIN	Test Row Input Voltage: This pad may be used to set a voltage for the test row in the chip.	TA
30, 31, 32, 33	TESTDET (4-1)	Test Detector Pads: These 4 pads provide a means of connecting to the 4 test detectors. The position of the test detectors is outlined in the Mechanical Drawing, 101-9901-80.	TD
25 and un-named	TESTOUT and un-named	DO NOT CONNECT TO THESE PADS ! Bonding to these pads could permanently damage the performance of the chip. These pads are used for ROIC factory testing only.	

5.0 Theory of Operation

A general description of the ISC9901 operation is given in this section.

Input Circuit

The Standard 640 uses a direct injection input circuit as shown in Figure 3. Detector current flows through the input gate transistor and charges up the integration capacitor. The anti bloom gate keeps the input circuit from saturating. The voltage on the integration capacitor is stored and multiplexed to the column amplifier during readout. The detector bias voltage may be controlled by applying a bias on the Vdet_adj pad when in Default mode. The detector bias is also

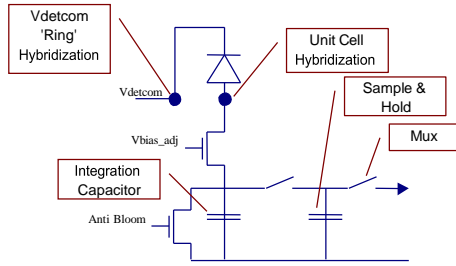


Figure 3. Simplified Unit Cell Schematic

adjustable using the Serial Control Register when operating the device in Command Mode. Adjusting the detector bias this way provides approximately 4-5 mV per count. The approximate relationship between the Vdet_adj input and the detector bias is shown in Figure 4.

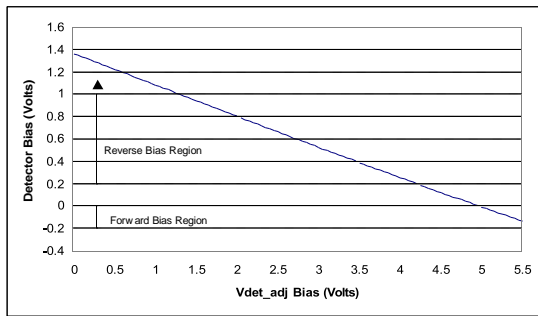


Figure 4. Detector Bias vs. Vdet_adj voltage

Column Amplifier

The column amplifier, shown in Figure 5, provides sample/hold, amplification, and skimming functions. The signal from the unit cell is sampled and held onto the column amplifier. The amplifier gain is controlled by the Gain0 and Gain1 pins when in Default Mode or by providing gain data to the Serial Control Register when in Command Mode. The relative gain is adjustable from 1 to approximately 4. A global offset function (also known as skimming) is implemented with the column amplifier and is available in both operation modes. To operate skimming, the Vos pad is set to a voltage greater than the voltage on Vref pad. The Vos voltage range is from Vref to Vpos, which corresponds to offsetting from 0 to 100% of full well. The column amplifier is also used to drive the output multiplexer bus.

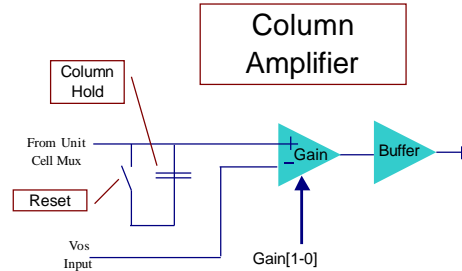


Figure 5. Column Amplifier Block Diagram

Output Multiplexer and Buffers

The ISC9901 may be run using from one, two, or four outputs. A reference output can also be enabled. Routing of a given column amplifier to a given output buffer is accomplished through the output multiplexer, shown in Figure 6. The maximum output data rate supported for single output mode is 12.3MHz over an 80K to 300K operating temperature range. For 2 or 4 output mode, operation a rate of 10MHz per output can be attained over the 80K to 300K temperature range. For single output mode, all pixels are readout through OutA. When using multiple outputs, pixels are assigned to a specific output channel, and will be read out through only that channel, regardless of the

invert/revert, windowing, and/or line repeat modes selected.

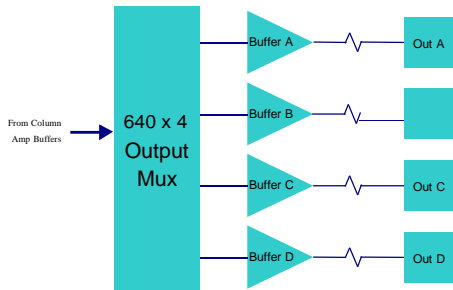


Figure 6. Output Multiplexer and Buffers

Integration

The Standard 640 device features snapshot mode integration, where all pixels integrate simultaneously. The integration process is controlled by the FSYNC clock and operates in Integrate-Then-Read mode only.

Figure 7 shows a timing pattern for operation of the Standard 640 device in the Integrate-Then-Read mode. The rising edge of the FSYNC clock pulse marks the beginning of the frame time. This is followed immediately by a sequence of LSYNC pulses that produce a readout sequence. Note that in this case the FSYNC clock remains high until the readout sequence has been completed. The integration time occurs after the readout time, resulting in a frame time that is approximately equal to the readout time plus the integration time. This results in a maximum frame rate that is a function of integration time.

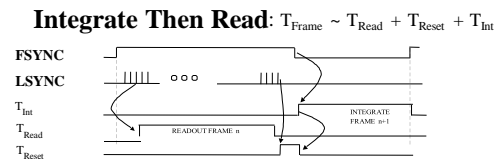


Figure 7. Integrate-Then-Read timing diagram

Biasing the Detector

It is important to bond the ISC9901 based upon the specific bias requirements for the type of detector being hybridized. There are two pads on the ISC9901 which define the detector bias interface. The first of these, the VDETCOM pad, is connected to a ring of detector common bumps that surround the active detectors. The Mechanical Interface Database (Doc # 101-9901-61) and application note “How to Interpret and Use the Mechanical Interface Database for the ISC9901” (Doc # 400-9901-21), provide additional information on this structure. The voltage applied to the VDETCOM pad sets the bias for detector common. A voltage of 0 to 6.0 volts referenced to VNEG (at 0 volts) may be supplied to this pad.

The second interface pad is the VPOS_REF pad. The internal detector bias generation circuitry is referenced to VPOS_REF. The ISC9901 output signal VPOS_REF (~5.5V) provides the IC’s internal reference point for the detector bias generation circuit. Any externally supplied bias generator must be referenced to VPOS_REF and not GND.

Two modes of supplying bias to the detectors are supported. For high detector bias applications (QWIP, PIN) it is advisable to reference a system supplied VDETCOM bias generator to the ISC9901 VPOS_REF pad signal. This does not imply applying a bias to VPOS_REF.



For low reverse bias voltage detectors (InSb, HgCdTe), the VDETCOM pad and VPOS_REF pad are connected together by the end user. Do not apply any bias to the VPOS_REF pad. The VPOS_REF pad is a low impedance voltage output pad from the ISC9901 to the system. Applying a bias to this pad may permanently damage the ISC9901 device. The VDETCOM pad must be connected and biased for correct operation.

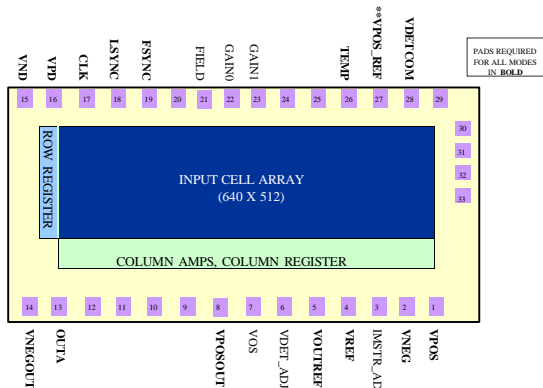
6.1 Modes of Operation

The ISC9901 has two operation modes, the simplified Default Mode and the programmable Command Mode which utilizes the advanced features of the ROIC.

Default Mode

This mode provides a simple interface, with reduced external electronics and power dissipation, for applications where advanced ROIC features or high-speed performance are not required. The Default Mode does not use the on chip Serial Control Register. Therefore, advanced features such as windowing, invert/revert and multiple data outputs are not available. The Default Mode supports operation with both high and low reverse bias detectors by using a special biasing procedure. In Default Mode the ISC9901 operates with the following configuration:

- single output
- variable gain
- full window
- normal scan order, interlaced readout
- no reference output
- supporting NTSC or PAL video timing
- maximum output rate 12.3MHz
- skimming



A total of 19 interconnects are required for Default Mode as shown in Figure 8.

Figure 8. Default Mode Bond Pad Diagram

Command Mode

Command Mode operation utilizes the on chip Serial Control Register to control device modes and advanced readout features. The fields of the Serial Control Register are illustrated in Figure 9. To operate in this mode, the DATA pad must be used to load control words into the Serial Control Register. The settings in this register determine the gain state, detector bias setting, power bias control, master current bias, skimming setting, output mode, window size, window position, image transposition and test mode. Master clock frequencies up to 5 MHz (10 MHz output rate) are supported when operating in the Command Mode.

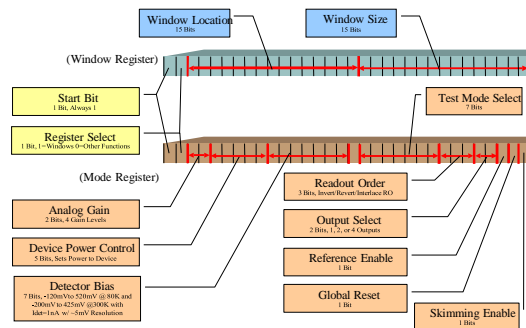


Figure 9. Serial Control Register Fields

There are 16-20 interconnects required, depending on the number of outputs and options invoked. The Command Mode bond pad diagram is shown in Figure 10.

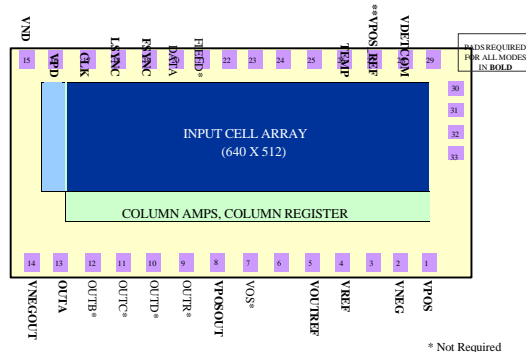


Figure 10. Command Mode Bond Pad Diagram

Output Modes

The ISC9901 can be configured to support one, two, four outputs with or without an output reference. In order to invoke any output mode other than single output, with no reference output, the device must be operated in Command Mode. For single output mode, all pixels are read out through OutA. When using multiple outputs, pixels are assigned to a specific output channel, and will be read out through only that channel, regardless of the image transposition (invert/revert), and windowing modes selected.

The lowest left-hand pixel is defined as pixel (0,0), where this annotation signifies the pixel at location row 0, column 0 of the ISC9901 device. Pixel (0,0) is the first pixel to be read out in using default settings for the invert/revert, windowing, and line repeat features. This mode of operation is chosen for a normal 'inverting optic'. Given this type of optic, a 'normal' raster scan image will be presented by placing the bottom row (row 0) at the 'bottom' of a camera system.

When two outputs are selected, the first pixel is presented at OutA, and the second pixel is presented at OutB. Alternate pixels are presented at the A and B output channels, respectively. When four outputs are selected, the first pixel is presented at OutA, the second pixel is presented at OutB, the third pixel at OutC, and the fourth at OutD.

Alternating in four pixel increments, pixels are presented at the A, B, C and D output channels, respectively. Figure 11. shows the assigned channels and readout order for four outputs and the various modes.

7.0 Physical Characteristics

The ISC9901 is built using a standard 0.6 micron CMOS process with triple metal and double polysilicon layers. The die size is 14.65 x14.71 mm as measured to the edge of the scribe lane. The die are processed on 5 inch (125mm) wafers which have a thickness of 625µm +/- 25µm. There are 37 die per wafer with a 200µm scribe lane in both the x and y direction. There are two variants of the design with different integration capacitor size, 350fF or 150fF. Devices with the 350fF capacitor are referred to as ISC9901-1 and devices with 150fF capacitor are referred to as ISC9901-2. A Mechanical Interface Database is delivered with the ISC9901 wafers. This database contains the detailed information required to design detector arrays for the ISC9901 readout device.

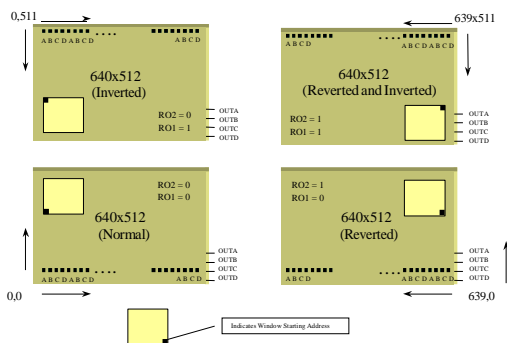


Figure 11. Four Output Mode Readout Order

WARNING ! Electrostatic Discharge Sensitive Device
 Electrostatic charges as high as 4000V readily accumulate on the human body and test equipment. This can discharge with out detection and cause permanent damage. The ISC9801 features proprietary ESD protection circuitry, however permanent damage may occur on devices subjected to high energy electrostatic discharges. Proper ESD precautions are recommended to avoid performance degradation or loss of functionality.